

*for immediate release*

## Sonoscan<sup>®</sup> to Demonstrate “Operator Free” 300mm Wafer Handler at Semicon West

Elk Grove Village IL, May 14, 2009 – Sonoscan, Inc., will demonstrate the functionality of its new AW300™ series robotic bonded wafer handler at Semicon West in San Francisco’s Moscone Center from July 14 to July 16.

The new system extends the 10-year legacy of Sonoscan’s Automated Wafer (AW) inspection systems, the first of which was made in 1999, based on C-SAM<sup>®</sup> proven technology.

The AW300 carries out robotic handling and acoustic imaging of bonded wafer pairs up to 300mm in diameter. Acoustic imaging is a critical step for finding tiny but lethal defects that can occur in bonded wafers. Robotic handling makes it unnecessary for operators to handle the wafer pairs.

In addition, the AW300 uses twin transducers to scan two wafer pairs simultaneously. At the same time, the two previously scanned wafers are being dried and returned to their carriers. Four wafer pairs are thus being processed at the same time.

The result is very high throughput for 300mm wafers. High operating speed, combined with very high resolution Sonoscan technology transducers, gives tremendous leverage in identifying defects that can harm both yield and reliability in wafer pairs that often contain thousands of devices.

The AW300 is integrated with an industry standard and proven EFEM (Equipment Front End Module) that is SECS/GEM ready, accommodates single or multiple load ports and utilizes either vacuum or edge grip end effectors. The scanner system utilizes linear motors and is inertially balanced for vibration free operation.

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